

Title (en)

HEAT STABLE MOLDED PHENOLIC RESIN ARTICLE.

Title (de)

HITZEBESTÄNDIGER GEFORMTER GEGENSTAND AUS PHENOLHARZ.

Title (fr)

ARTICLE EN RESINE PHENOLIQUE MOULEE STABLE A LA CHALEUR.

Publication

**EP 0073191 A1 19830309 (EN)**

Application

**EP 81901736 A 19810302**

Priority

US 8100253 W 19810302

Abstract (en)

[origin: WO8203080A1] A heat stable molded phenolic resin article comprising, in percent by weight, from about 20 to about 70 percent of a phenolic resin, from about 3 to about 25 percent of an acrylonitrilebutadiene elastomer, and from about 15 to about 70 percent of a silicate mineral. Also a molding composition comprising, in percent by weight, from about 20 to about 70 weight percent of a phenol-aldehyde thermosettable resin, from about 3 to about 25 weight percent of an acrylonitrilebutadiene elastomer, and from about 15 to about 70 weight percent of silicate mineral.

Abstract (fr)

Article en resine phenolique moulee stable a la chaleur comprenant, en pourcentages ponderaux, environ 20 a 70% d'une resine phenolique, environ 3 a 25% d'un elastomere d'acrylonitrile butadiene et environ 15 a 70% d, un silicate mineral. Composition de moulage comprenant, en pourcentages ponderaux, environ 20 a 70% en poids d'une resine thermodurcissable de phenol-aldehyde, environ 3 a 25% en poids d'un elastomere d'acrylonitrile butadiene, et environ 15 a 70% en poids d'un silicate mineral.

IPC 1-7

**C08L 61/06**

IPC 8 full level

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CPC (source: EP)

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